

Hybrid Package with Non-Insertable and Insertable Conductive Features,
Complementary Receptacle, and Methods of Fabrication, Assembly, and Operation
Therefor

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Abstract of the Disclosure

A hybrid electronic circuit package (102, Figure 1) includes non-insertable
conductive features (110) and insertable conductive features (112) at a surface of the
package. A hybrid receptacle (120), such as a socket, for example, includes non-
10 insertable contacts (124) and insertable contacts (126), which are positioned in a
complementary manner with the non-insertable and insertable features of the package. A
vertical securement device (132, 134, 136) applies a vertical compressive force to the
package (102) to compress the non-insertable features (110) against the non-insertable
contacts (124). Further, a normal force securement device can be used to provide a
15 sustained normal force to compress the insertable features and contacts together. In one
embodiment, the non-insertable features are land grid array lands and the insertable
features are low insertion force features.

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